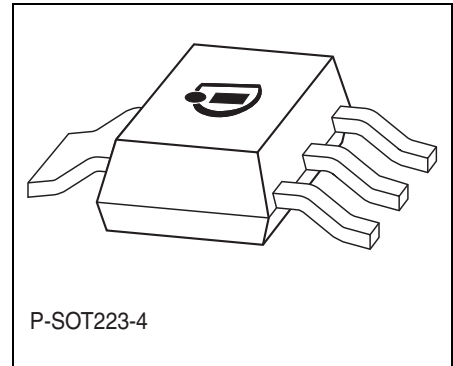


Data Sheet

Features

- Output voltage 3.3 V or adjustable
- 1.0 A output current
- Low drop voltage < 1.2 V @ 800 mA
- Short circuit protected
- Overtemperature protected
- Operating range up to 15 V
- Industrial type



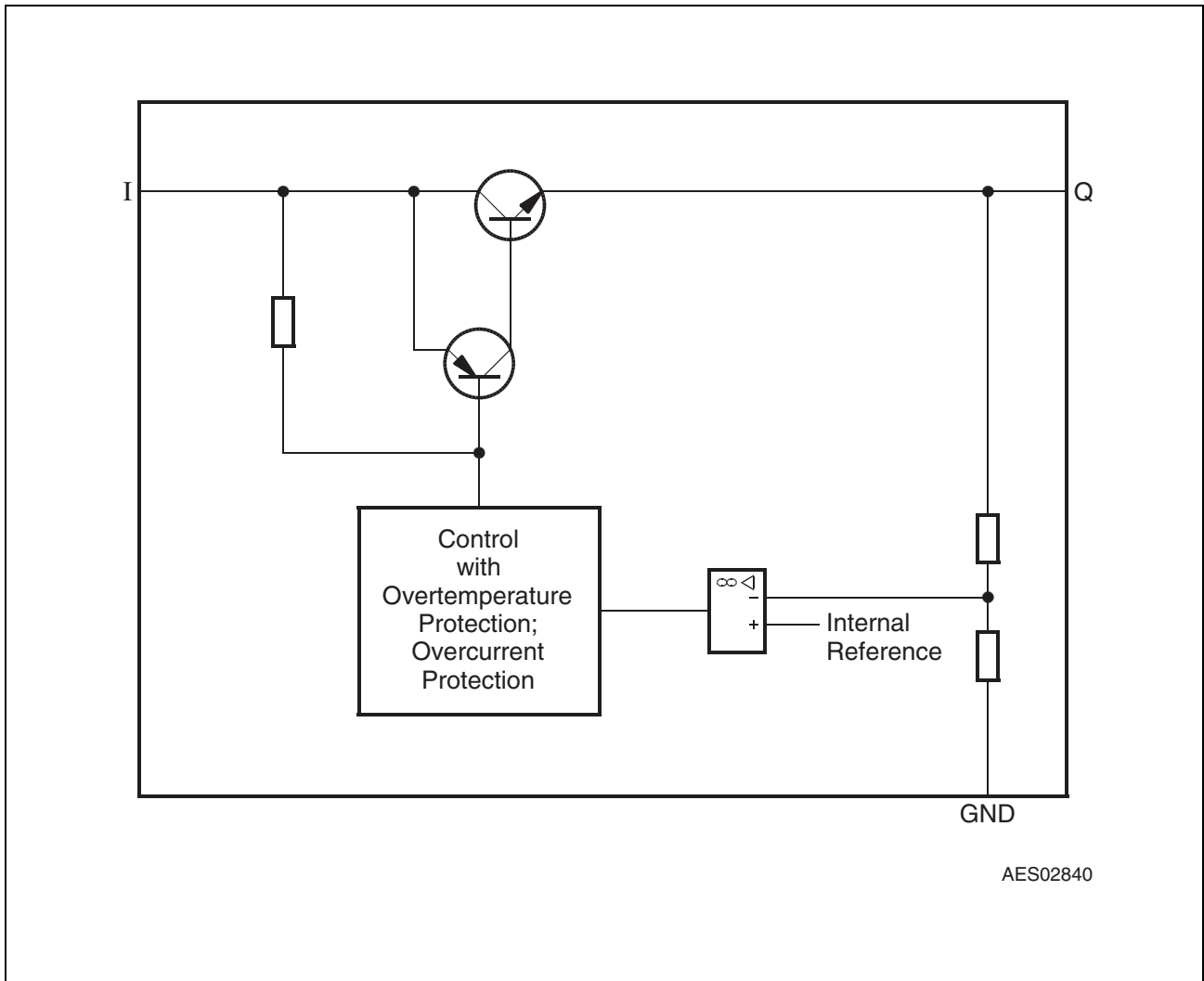
Functional Description

The IFX 1117 is a monolithic integrated fixed NPN type voltage regulator that can supply loads up to 1.0 A. The device is housed in the small surface mounted SOT223 package. The IC is equipped with additional protection against overload, short circuit and overtemperature.

The IFX 1117 GSV33 supplies a regulated output voltage of 3.3 V ($\pm 2\%$). The IFX 1117 GSV supplies an output voltage with $\pm 2\%$ precision adjustable via an external voltage divider. The input voltage for the IFX 1117 GSV33 ranges from 4.5 V ($= V_Q + V_{DR}$) to 15 V for a load current of 800 mA, for the maximum load current of 1.0 A a minimum input voltage of 4.7 V is required. The drop voltage V_{DR} ranges from 1.1 V to 1.4 V depending on the load current level.

The device operates in the temperature range of $T_j = 0$ to 125 °C.

Type	Ordering Code	Package
IFX 1117 GSV33	Q67006-A9681	P-SOT223-4-6
		P-SOT223-4-4
IFX 1117 GSV	Q67006-A9680	P-SOT223-4-6
		P-SOT223-4-4



AES02840

Figure 1 Block Diagram for Fixed Output Voltage IFX 1117 GSV33

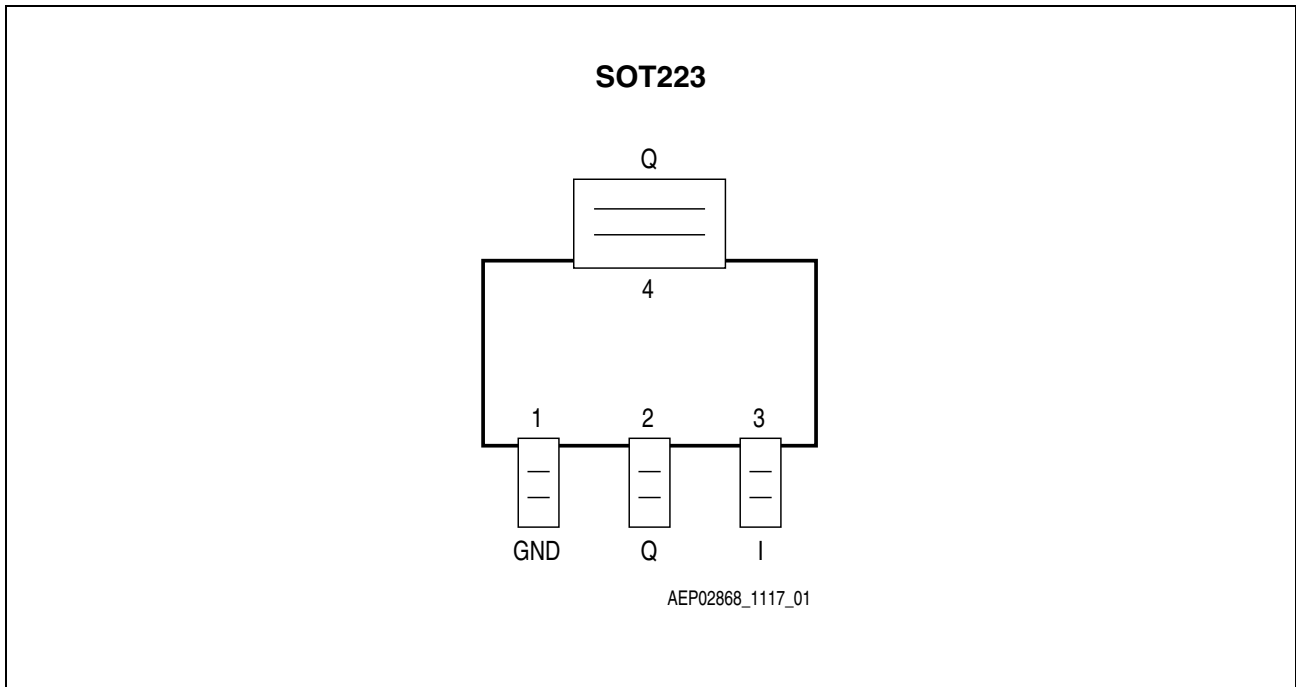


Figure 2 Pin Configuration IFX 1117 GSV33 (top view)

Table 1 Pin Definitions and Functions IFX 1117 GSV33

Pin No.	Symbol	Function
1	GND	Ground
2	Q	Output; Connect output pin to GND via a capacitor $C_Q \geq 10 \mu\text{F}$ with $\text{ESR} \leq 20 \Omega$ (see also graph “Region of Stability”)
3	I	Input
4 (Heatsink)	Q	Output; Connect to pin 2

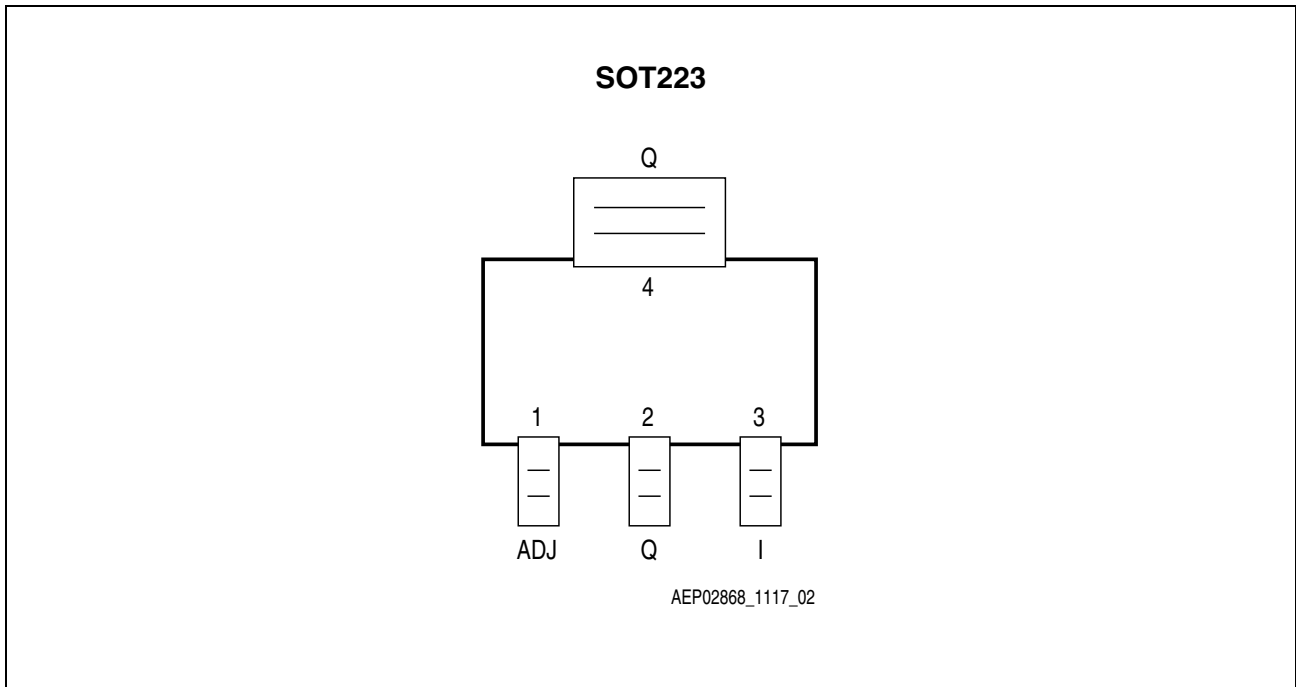


Figure 3 Pin Configuration IFX 1117 GSV (top view)

Table 2 Pin Definitions and Functions IFX 1117 GSV

Pin No.	Symbol	Function
1	ADJ	Adjust ; defines output voltage level by external voltage divider between Q, ADJ and GND.
2	Q	Output ; Connect output pin to GND via a capacitor $C_Q \geq 10 \mu\text{F}$ with $\text{ESR} \leq 20 \Omega$ (see also graph “Region of Stability”).
3	I	Input
4 (Heatsink)	Q	Output ; Connect to pin 2

Table 3 Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit	Test Condition
		Min.	Max.		
Input - Output Voltage Difference (variable device only)					
Voltage	$V_I - V_Q$	-0.3	20	V	–
Input Voltage (fixed voltage version only)					
Voltage	V_I	-0.3	20	V	–
Output					
Voltage	V_Q	-0.3	20	V	–
Current	I_Q	–	–	–	Internally limited
ESD Rating					
Electrostatic discharge voltage	V_{ESD}	-2	2	kV	Human Body Model
Temperature					
Storage temperature	T_{stg}	-50	150	°C	–
Junction temperature	T_j	-40	150	°C	–

Note: Stresses above those listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 4 Operating Range

Parameter	Symbol	Limit Values		Unit	Remarks
		Min.	Max.		
Input Voltage	V_I	$V_Q + V_{DR}$	15	V	–
Junction temperature	T_j	0	125	°C	–

Table 5 Thermal Resistance

Junction ambient	R_{thja}	–	164	K/W	P-SOT223, no airflow, no heat sink area
		–	81	K/W	P-SOT223 300 mm ² heat sink area
Junction case	R_{thjc}	–	4	K/W	–

Note: In the operating range, the functions given in the circuit description are fulfilled.

Characteristics 3.3 V Fixed Output Voltage Device IFX 1117 GSV33
0 °C < T_j < 125 °C; V_I = 5 V, I_Q = 10 mA; unless otherwise specified.

Parameter	Symbol	Limit Values			Unit	Measuring Conditions
		min.	typ.	max.		
Output voltage	V _Q	3.23 5	3.300	3.36 5	V	0 mA ≤ I _Q ≤ 800 mA 4.7 V ≤ V _I ≤ 10 V
Output voltage	V _Q	–	3.300	–	V	0 mA ≤ I _Q ≤ 1000 mA; 4.7 V ≤ V _I ≤ 15V
Line regulation	ΔV _Q	–	1	6	mV	4.7 V ≤ V _I ≤ 15V
Load regulation	ΔV _Q	–	1	10	mV	0 mA ≤ I _Q ≤ 800 mA; ¹⁾
		–	2	–	mV	0 mA ≤ I _Q ≤ 1.0 A ¹⁾
Drop voltage	V _{DR}	–	1.00	1.10	V	I _Q = 100 mA ²⁾
Drop voltage	V _{DR}	–	1.05	1.15	V	I _Q = 500 mA ²⁾
Drop voltage	V _{DR}	–	1.10	1.20	V	I _Q = 800 mA ²⁾
Drop voltage	V _{DR}	–	1.30	1.40	V	I _Q = 1.0 A ²⁾
Current consumption; I _q = I _I – I _Q	I _q	–	5	10	mA	I _Q = 10 mA
Temperature stability	ΔV _Q	–	16.5	–	mV	³⁾
Long Term Stability	–	–	0.3	–	%	³⁾
Current limit	I _{Qmax}	1100	–	2250	mA	V _Q = 0.5 V
RMS Output Noise	–	–	30	–	ppm	ppm of V _Q , T _j = 25 °C 10 Hz ≤ f ≤ 10 kHz ³⁾
Power Supply Ripple Rejection	PSRR	60	65	–	dB	f _r = 120 Hz, V _r = 1 V _{PP} ³⁾

1) Measured at constant junction temperature

2) Drop voltage measured when the output voltage has dropped 100 mV from the nominal value obtained at V_I = 5.0 V.

3) Specified by design; not subject to production test.

Characteristics Adjustable Output Voltage Device IFX 1117 GSV
0 °C < T_j < 125 °C; V_I = 5 V, I_Q = 10 mA; unless otherwise specified.

Parameter	Symbol	Limit Values			Unit	Measuring Conditions
		min.	typ.	max.		
Reference voltage	V _Q	1.22 5	1.250	1.27 0	V	10 mA ≤ I _Q ≤ 800 mA; 1.4 V ≤ (V _I -V _Q) ≤ 10 V
Output voltage	V _Q	–	1.250	–	V	10 mA ≤ I _Q ≤ 1000 mA; 2.65 V ≤ V _I ≤ 15 V
Line regulation	ΔV _Q	–	0.035	0.2	% ¹⁾	1.5 V ≤ (V _I -V _Q) ≤ 13.75 V
Load regulation	ΔV _Q	–	0.2	0.4	% ¹⁾	10 mA ≤ I _Q ≤ 800 mA; ²⁾
		–	0.25	–	% ¹⁾	10 mA ≤ I _Q ≤ 1.0 A ²⁾
Drop voltage	V _{DR}	–	1.00	1.10	V	I _Q = 100 mA ³⁾
Drop voltage	V _{DR}	–	1.05	1.15	V	I _Q = 500 mA ³⁾
Drop voltage	V _{DR}	–	1.10	1.20	V	I _Q = 800 mA ³⁾
Drop voltage	V _{DR}	–	1.30	1.40	V	I _Q = 1.0 A ³⁾
Minimum Load Current ⁴⁾	I _q	–	1.7	5.0	mA	V _I = 15 V
Adjust Current	I _{ADJ}	–	100	120	μA	I _Q = 10 mA
Adjust Current Change	ΔI _{ADJ}	–	2	5	μA	1.4 V ≤ (V _I -V _Q) ≤ 13.6 V; 10 mA ≤ I _Q ≤ 800 mA
Temperature stability	ΔV _Q	–	0.5	–	% ¹⁾	⁵⁾
Long Term Stability	–	–	0.3	–	% ¹⁾	⁵⁾
Current limit	I _{Qmax}	1100	–	2250	mA	V _Q = 0.5 V
RMS Output Noise	–	–	30	–	ppm	ppm of V _Q , T _j = 25 °C 10 Hz ≤ f ≤ 10 kHz ⁵⁾
Power Supply Ripple Rejection	PSRR	65	70	–	dB	f _r = 120 Hz, V _r = 1 V _{PP} ⁵⁾

1) Related to V_Q

2) Measured at constant junction temperature

3) Drop voltage measured when the output voltage has dropped 100 mV from the nominal value obtained at V_I = 5.0 V.

4) Minimum load current required to maintain regulation

5) Specified by design; not subject to production test.

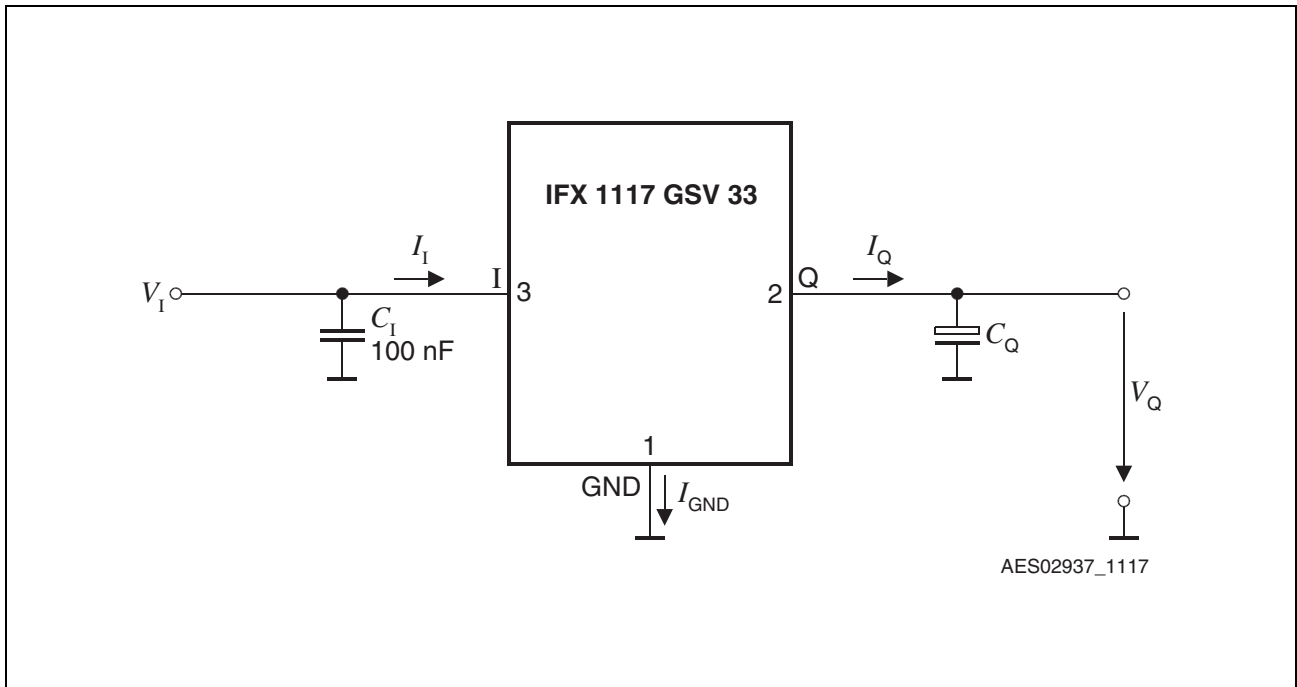


Figure 4 Measuring Circuit

Application Information

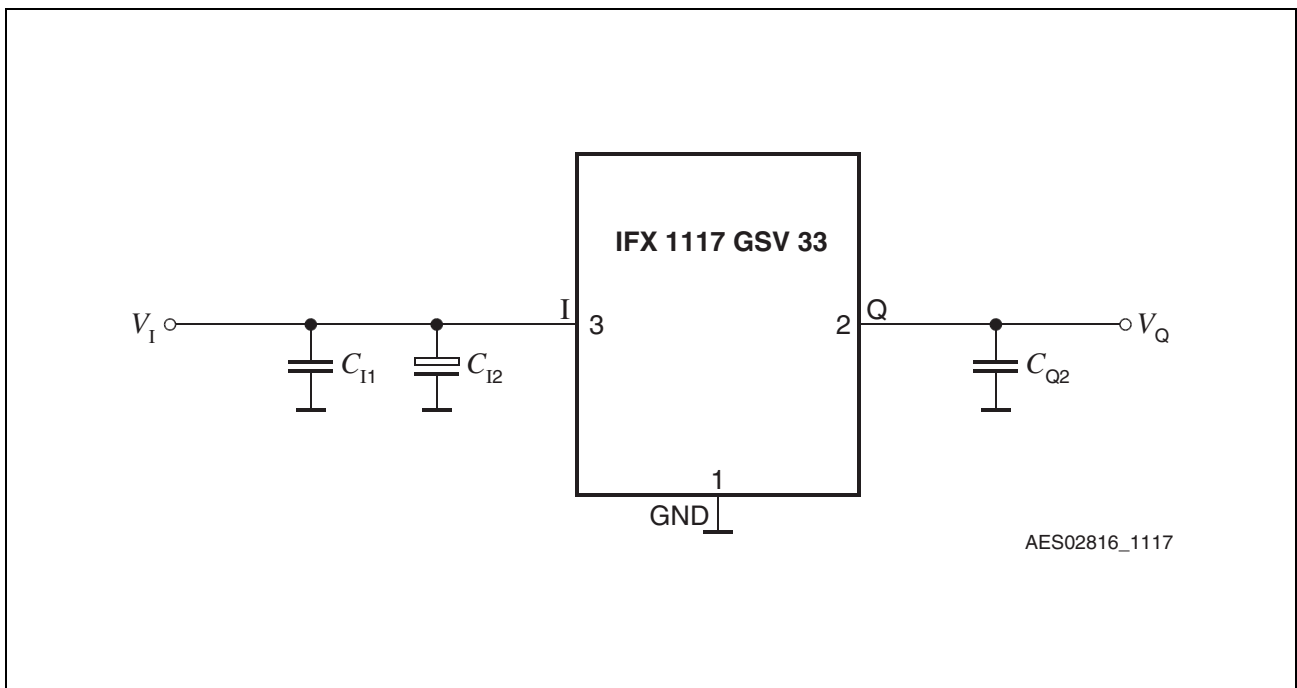


Figure 5 Typical Application Circuit IFX 1117 GSV33

Output

The IFX 1117 requires a 10 μF output capacitor with $\text{ESR} \leq 20 \Omega$ for the stability of the regulation loop. The use of a tantalum output capacitor is recommended.

For the adjustable device IFX 1117 GSV the output voltage level can be defined by a voltage divider between Q, ADJ and GND.

The output voltage calculates:

$$V_Q = V_{\text{REF}} \times \left(1 + \frac{R_2}{R_1}\right) + I_{\text{ADJ}} \times R_2 \quad (1)$$

At the input of the regulator a capacitor is recommended to compensate line influences. As a minimum a 100 nF ceramic input capacitor should be used. If the regulator is used in an environment with long input lines an input capacitance of 10 μF is suggested.

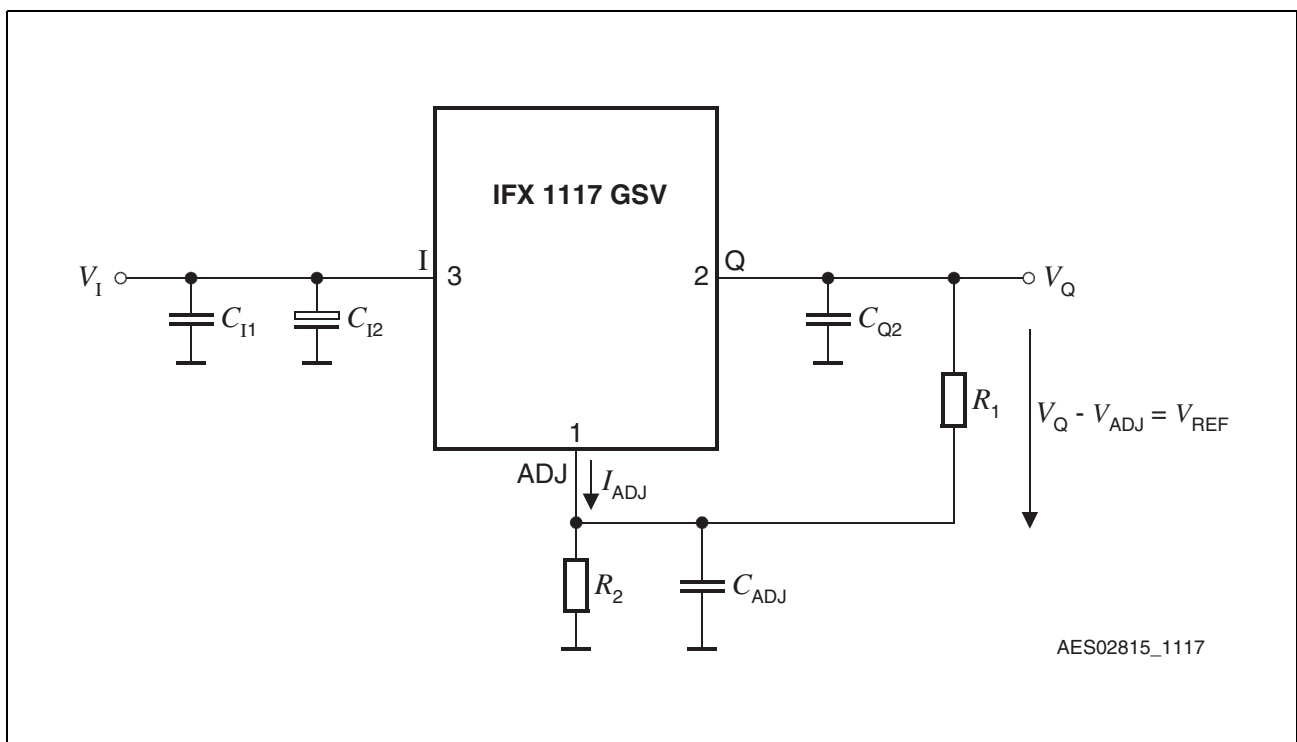
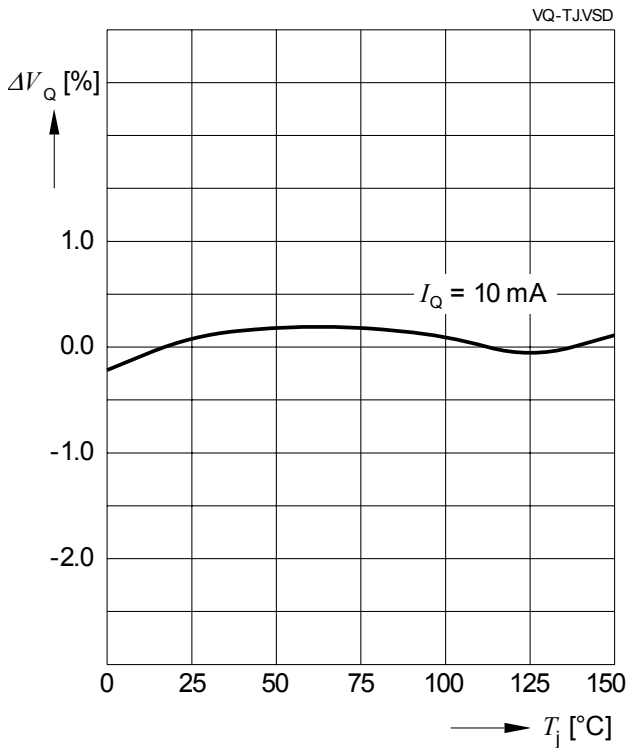


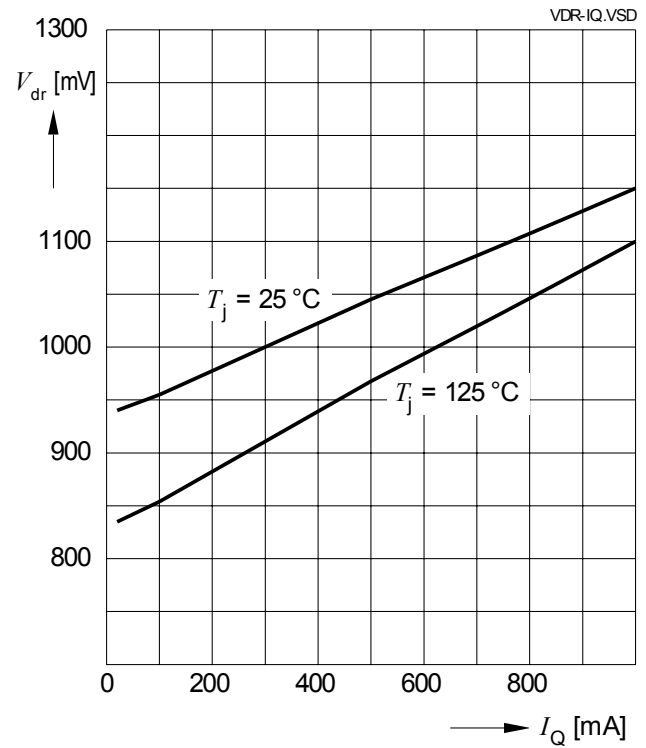
Figure 6 Typical Application Circuit IFX 1117 GSV

Typical Performance Characteristics

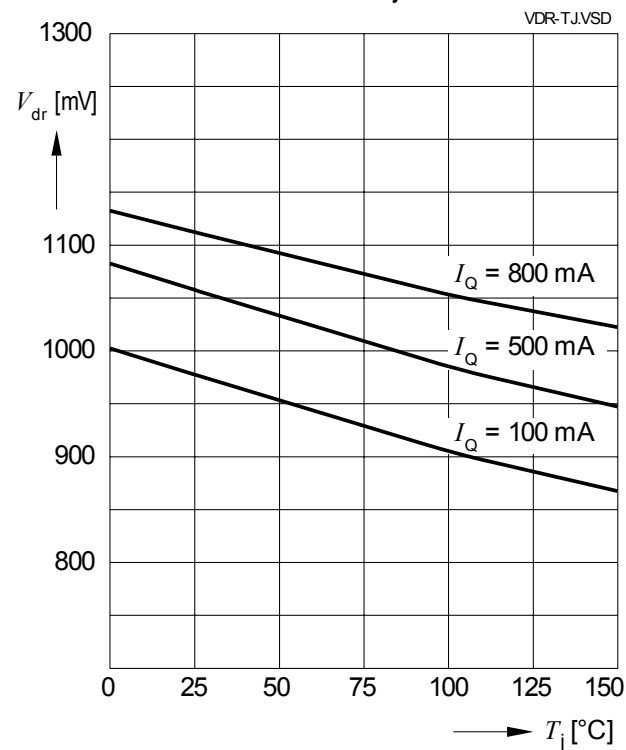
Output Voltage V_Q versus Junction Temperature T_j



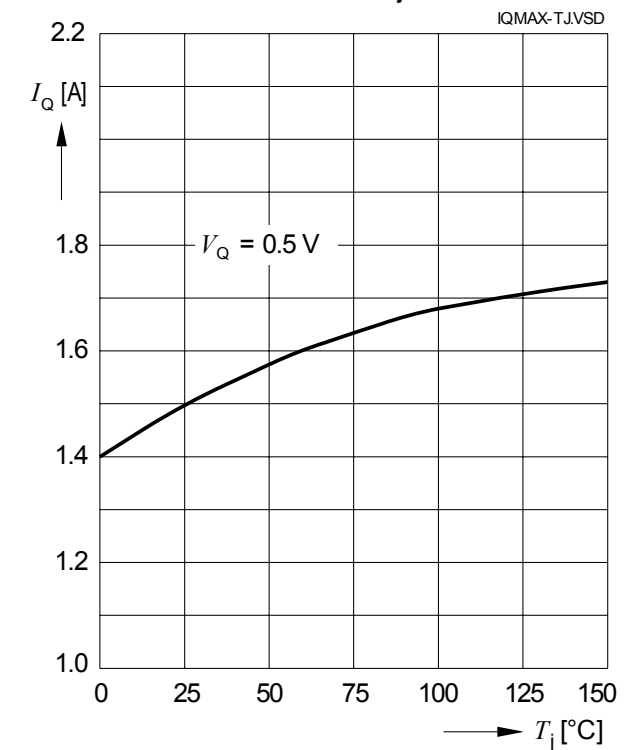
Dropout Voltage V_{dr} versus Output Current I_Q



Dropout Voltage V_{dr} versus Junction Temperature T_j

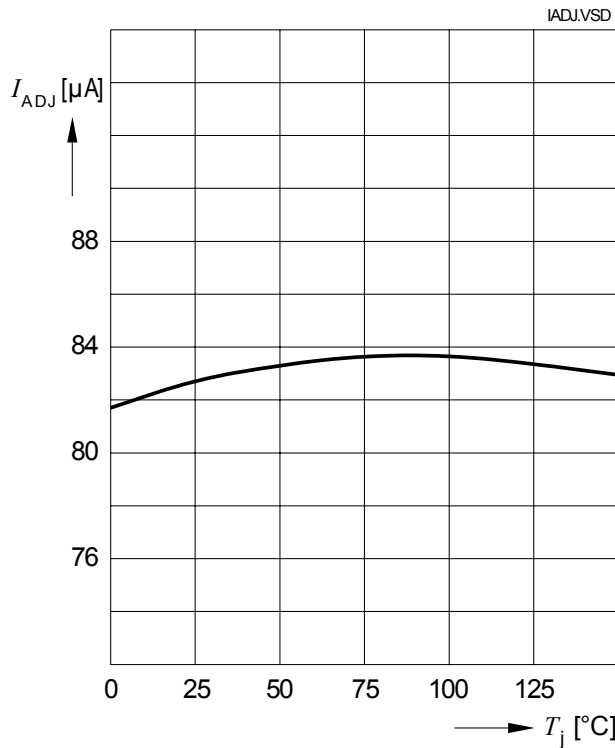


Maximum Output Current I_Q versus Junction Temperature T_j

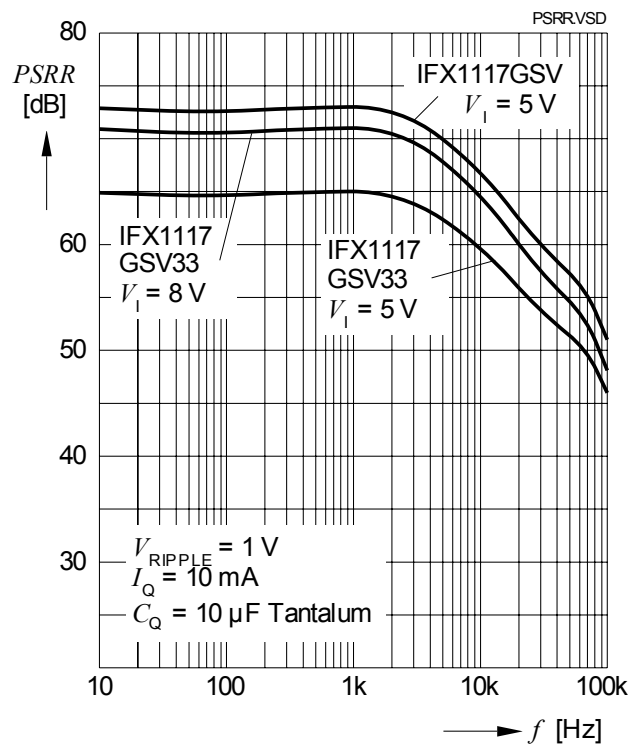


Typical Performance Characteristics

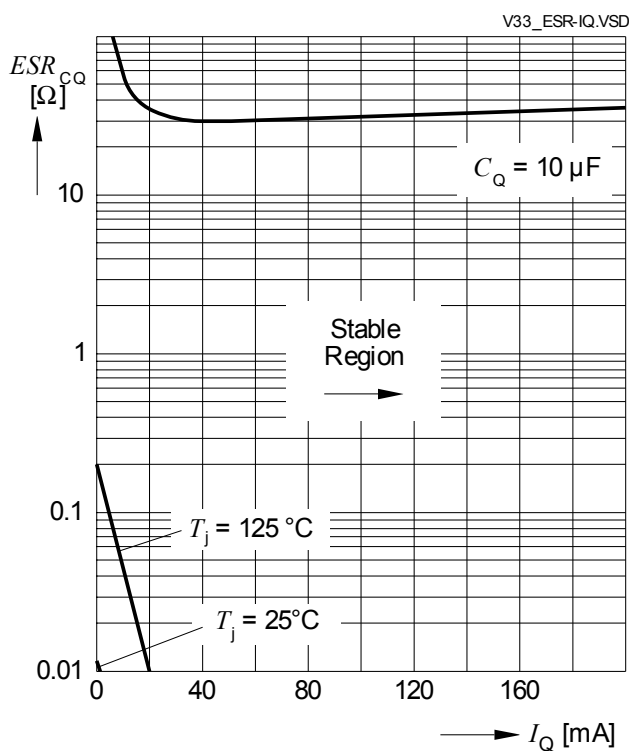
Adjust Pin Current I_{ADJ} versus Junction Temperature T_j



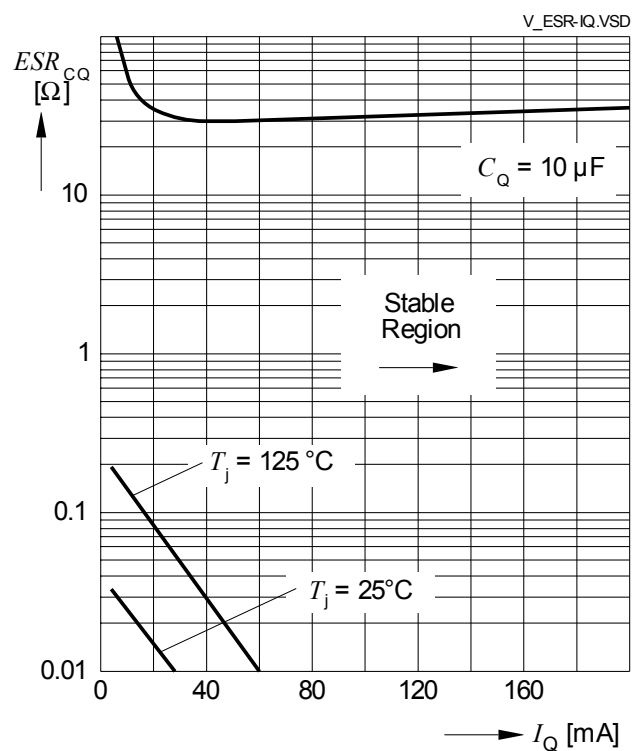
Power Supply Ripple Rejection $PSRR$ versus Frequency f



Region of Stability Version GSV33

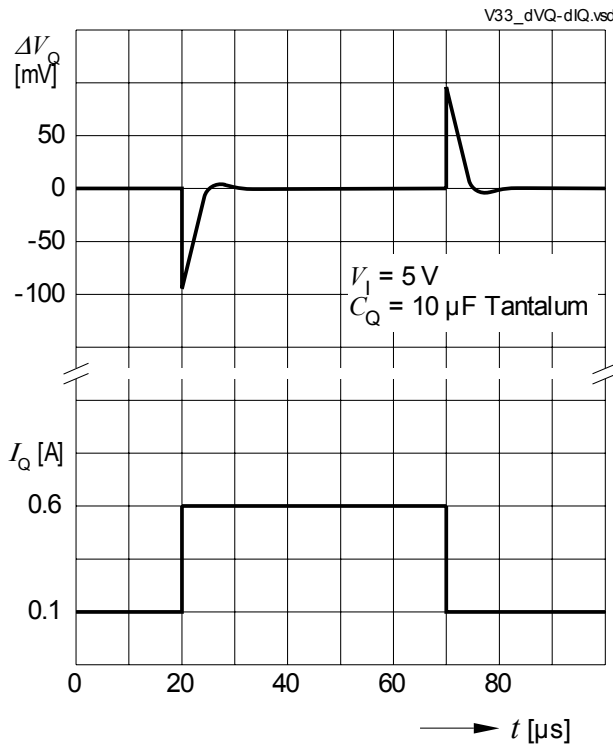


Region of Stability Version GSV

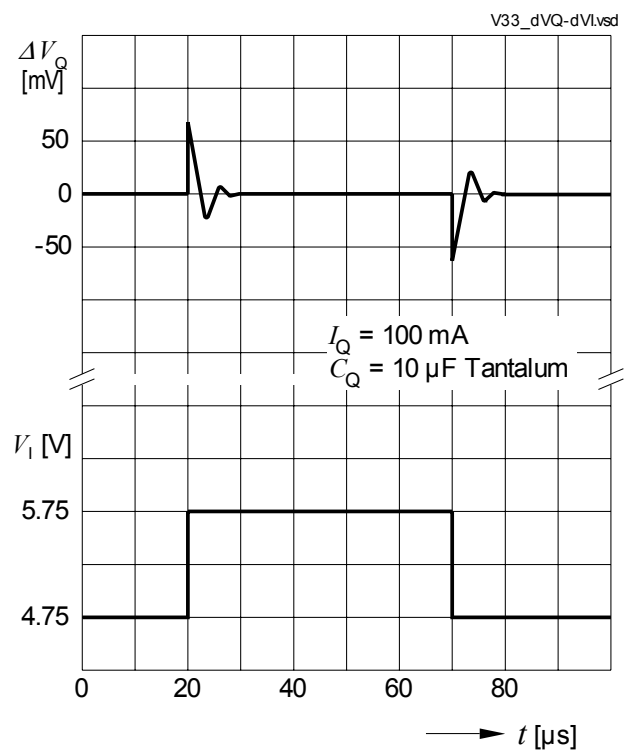


Typical Performance Characteristics

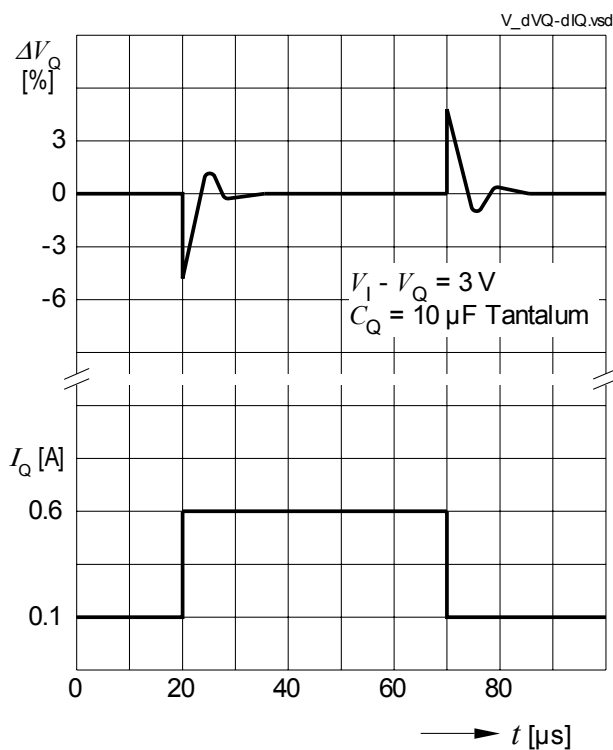
Load Transient Response Version GSV33



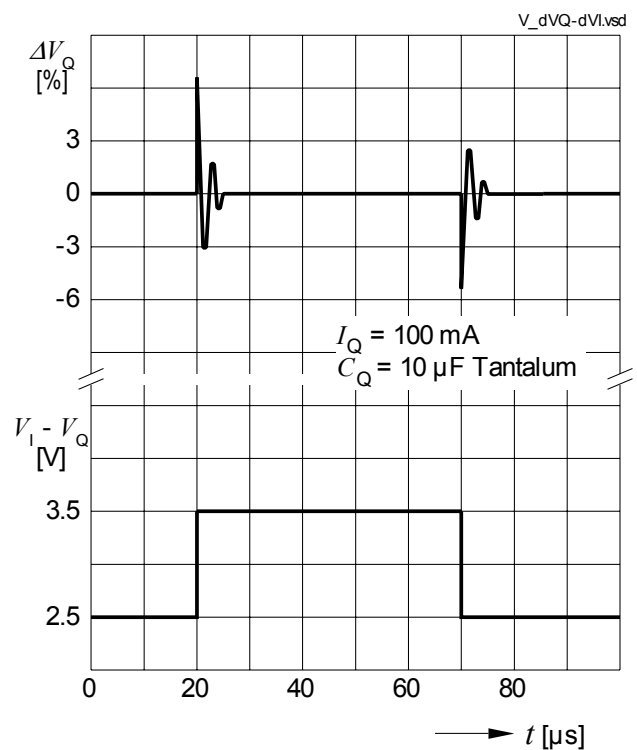
Line Transient Response Version GSV33



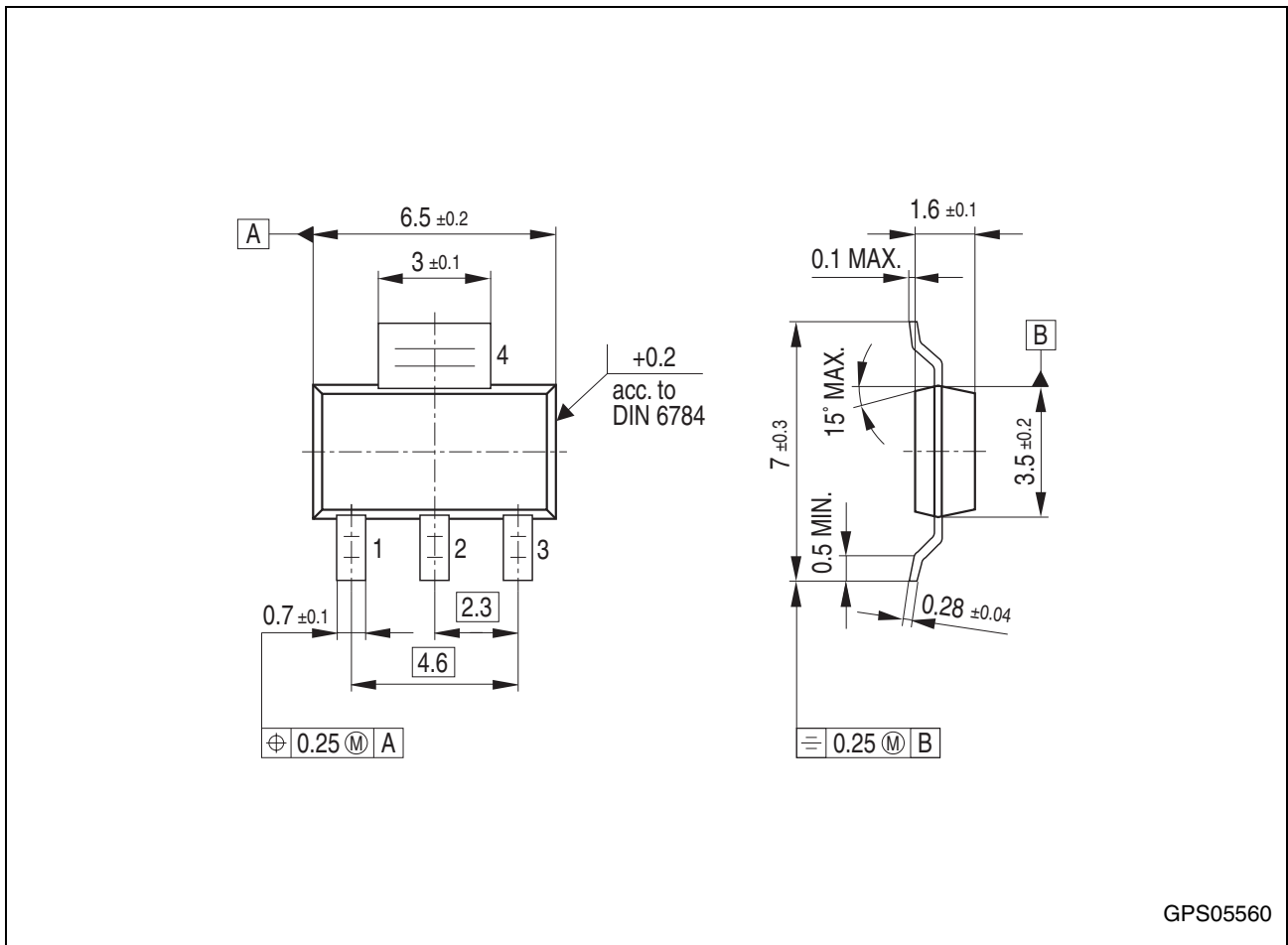
Load Transient Response Version GSV



Line Transient Response Version GSV



Package Outlines



GPS05560

Figure 7 P-SOT223-4-6, P-SOT223-4-4 (Plastic Small Outline Transistor)

You can find all of our packages, sorts of packing and others in our Infineon Internet Page “Products”: <http://www.infineon.com/products>.

SMD = Surface Mounted Device

Dimensions in mm

Revision History

Version	Date	Changes
Rev. 1.0	2004-06-01	Final Data Sheet
Rev. 1.1	2004-07-20	"Typical Performance Characteristics" graphs added.

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